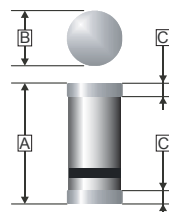


RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

FEATURES

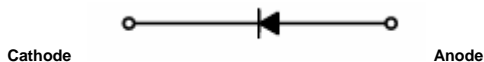
- SOD-80 (Mini-MELF) Package
- Surface Device Type Mounting
- Hermetically Sealed Glass
- Compression Bonded Construction
- All External Surfaces Are Corrosion Resistant And Terminals Are Readily Solderable
- RoHS Compliant
- Matte Tin (Sn) Lead Finish
- Color band Indicates Negative Polarity

SOD-80 (Mini-Melf)



REF.	Millimeter	
	Min.	Max.
A	3.30	3.70
B	1.40	1.60
C	0.28	0.50

ELECTRICAL SYMBOL



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Maximum Repetitive Reverse Voltage	V_{RRM}	250	V
Average Rectified Forward Current	$I_{F(AV)}$	200	mA
Non repetitive Peak Forward Current Pulse Width = 1.0 Second Pulse Width = 1.0 μ second	I_{FSM}	1.0 4.0	A
Power Dissipation	P_D	500	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	350	$^\circ\text{C} / \text{W}$
Junction, Storage Temperature	T_J, T_{STG}	200, -65 ~ +200	$^\circ\text{C}$

These ratings are limiting values above which the serviceability of the diode may be impaired.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameters	Symbol	Min.	Max.	Unit	Test Conditions
Breakdown Voltage	B_V	60	-	V	$I_R = 100\mu\text{A}$
		120	-		
		200	-		
		250	-		
Reverse Leakage Current	I_R	-	100	nA	$V_R = 50\text{V}$
		-	100		$V_R = 100\text{V}$
		-	100		$V_R = 150\text{V}$
		-	100		$V_R = 200\text{V}$
Forward Voltage	V_F	-	1.0	V	$I_F = 100\text{mA}$
Capacitance	C	-	5.0	pF	$V_R = 0\text{V}, f = 1\text{MHz}$
Reverse Recovery Time	T_{RR}	-	50	nS	$I_F = I_R = 30\text{mA}, I_{RR} = 3\text{mA}, R_L = 100\Omega$

CHARACTERISTICS CURVE

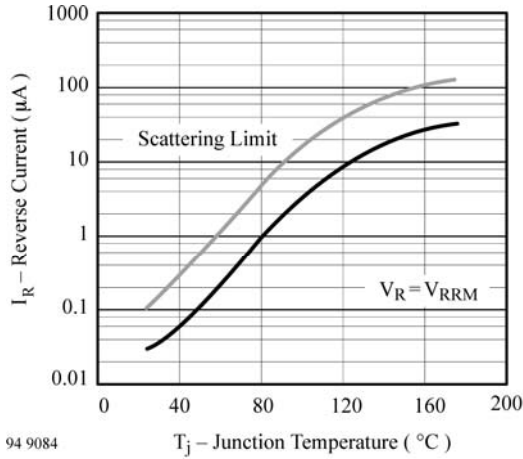


Figure 1. Reverse Current vs. Junction Temperature

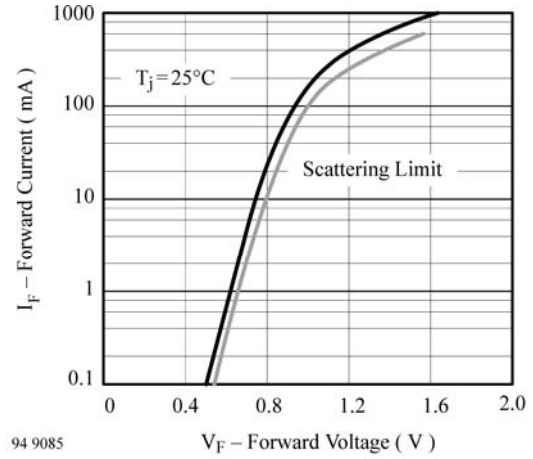


Figure 2. Forward Current vs. Forward Voltage

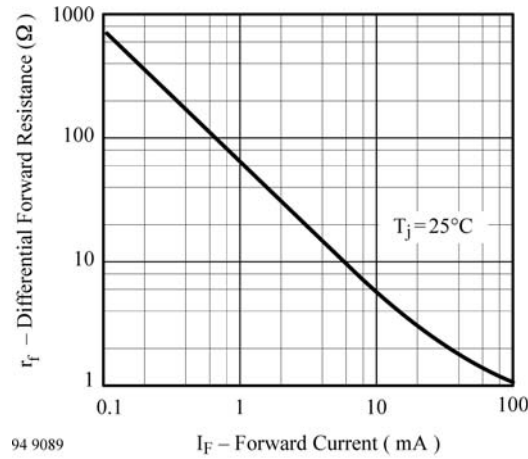


Figure 3. Differential Forward Resistance vs. Forward Current